ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Compo © Copyright 2005. IP international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute					* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Inform	nation															
Company name*		Company unique ID			τ	Unique ID Authority					Response Date*					
nsemi												2023-06-08				
Contact Name		Title - Contact			1	Phone - Contact*					Email - Contact*					
Product-Env-Stew	ards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized Repres	entative*	Title - Representative			1	Phone - Representative*					Email - Representative*					
Product-Env-Stew	ards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Request	er Item Number			Mfr Item Name			Effective Dat	Effective Date Version Manufacturing Signature		ing Site	V	Veight*	UOM	Unit Type		
				Synchronous Buck	ronous Buck MOSFET Driver		2023-06-08 T		ТН6		9	.1	mg	Each		
Ianufacturing	Proccess Informati	ion														
Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature		ure Max Tii	ne at Peak	Temperatu	ire Nun	nber of Reflow Cy	cles			
Matte Tin (Sn) - annealed C			CU Alloy 1				260 C 30			seconds 3						
omments																
vel 1 - maximum	time at peak temperatui	re during sol	dering is 10-3	30 seconds												
or more informat	ion regarding material c	composition]	please refer t	o page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.16	mg	Supplier	Silicon (Si)	7440-21-3		0.16	mg
Die Attach	0.07	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.014	mg
			Supplier	Silver (Ag)	7440-22-4		0.056	mg
Lead Frame	3.71	mg	Supplier	Silver (Ag)	7440-22-4		0.0371	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0045	mg
			Supplier	Iron (Fe)	7439-89-6		0.0872	mg
			Supplier	Copper (Cu)	7440-50-8		3.5801	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0011	mg
Mold Compound-Black	5.0	mg		Epoxy resin	proprietary data		0.25	mg
			Supplier	Phenolic Resin	Proprietary Data		0.115	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.25	mg
			Supplier	Carbon Black (C)	1333-86-4		0.02	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.115	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.25	mg
Plating	0.14	mg	Supplier	Tin (Sn)	7440-31-5		0.14	mg
Wire Bond	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0195	mg